Review Questions
Section 1: Contamination

Explain oxidation and its negative effect on soldering.

What can you do to protect circuit boards and components after they arrive at your facility?

What is the purpose of the solvent extract test?
Review Questions
Section 1: Contamination (cont’d)

Describe some examples of contamination and explain why they are a problem in electronics assembly?

What is the role of flux in the soldering operation?
Review Questions
Section 2: Other Handling Issues

Discuss the *intermetallic compound* and why scratches are a problem.

What is the best way to avoid scratches?

Why are *ladder style racks* a problem for storing circuit boards?

What are some examples of how circuit board assemblies are mishandled.
Review Questions
Section 2: Other Handling Issues (cont’d)

What is ESD and why does it need to be controlled?

What are some of the techniques used to control ESD?

Explain the pros and cons of the three main types of component packaging.

Why are lead skewing and coplanarity undesirable?